

30V P-Ch Power MOSFET

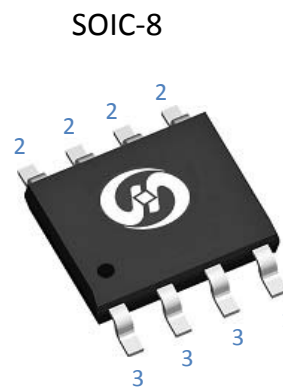
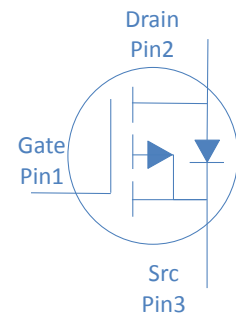
Feature

- ◇ High Speed Power Switching, Logic Level
- ◇ Enhanced Avalanche Ruggedness
- ◇ 100% UIS Tested, 100% Rg Tested
- ◇ Lead Free, Halogen Free

V_{DS}		-30	V
$R_{DS(on),typ}$	$V_{GS}=10V$	9.2	m Ω
$R_{DS(on),typ}$	$V_{GS}=4.5V$	10.7	m Ω
I_D (Silicon Limited)		-15	A

Application

- ◇ Hard Switching and High Speed Circuit
- ◇ DC/DC in Telecoms and Industrial



Part Number	Package	Marking
HTS130P03Z	SOIC-8	TS130P03Z

Absolute Maximum Ratings at $T_j=25^\circ\text{C}$ (unless otherwise specified)

Parameter	Symbol	Conditions	Value	Unit
Continuous Drain Current (Silicon Limited)	I_D	$T_C=25^\circ\text{C}$	-15	A
		$T_C=100^\circ\text{C}$	-9	
Drain to Source Voltage	V_{DS}	-	-30	V
Gate to Source Voltage	V_{GS}	-	± 20	V
Pulsed Drain Current	I_{DM}	-	-48	A
Avalanche Energy, Single Pulse	E_{AS}	$L=0.5\text{mH}, T_C=25^\circ\text{C}$	115	mJ
Power Dissipation	P_D	$T_A=25^\circ\text{C}$	1.7	W
Operating and Storage Temperature	T_J, T_{stg}	-	-55 to 150	$^\circ\text{C}$

Absolute Maximum Ratings

Parameter	Symbol	Max	Unit
Thermal Resistance Junction-Ambient	$R_{\theta JA}$	75	$^\circ\text{C/W}$
Thermal Resistance Junction-Lead	$R_{\theta JL}$	23	$^\circ\text{C/W}$

Electrical Characteristics at $T_j=25^{\circ}\text{C}$ (unless otherwise specified)
Static Characteristics

Parameter	Symbol	Conditions	Value			Unit
			min	typ	max	
Drain to Source Breakdown Voltage	$V_{(BR)DSS}$	$V_{GS}=0V, I_D=-250\mu A$	-30	-	-	V
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=-250\mu A$	-1.0	-1.3	-2.2	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{GS}=0V, V_{DS}=-30V, T_j=25^{\circ}\text{C}$	-	-	-1	μA
Gate to Source Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	± 100	nA
Drain to Source on Resistance	$R_{DS(on)}$	$V_{GS}=-10V, I_D=-12A$	-	9.2	13	m Ω
		$V_{GS}=-6V, I_D=-10A$	-	10.7	17	
Transconductance	g_{fs}	$V_{DS}=-5V, I_D=-15A$	-	28	-	S

Dynamic Characteristics

Input Capacitance	C_{iss}	$V_{GS}=0V, V_{DS}=-15V, f=1\text{MHz}$	-	2900	-	pF
Output Capacitance	C_{oss}		-	410	-	
Reverse Transfer Capacitance	C_{rss}		-	280	-	
Total Gate Charge	Q_g	$V_{DD}=-15V, I_D=-10A, V_{GS}=-10V$	-	48	-	nC
Gate to Source Charge	Q_{gs}		-	12	-	
Gate to Drain (Miller) Charge	Q_{gd}		-	14	-	
Turn on Delay Time	$t_{d(on)}$	$V_{DD}=-15V, V_{GS}=-10V, R_G=3\Omega,$	-	15	-	ns
Rise time	t_r		-	11	-	
Turn off Delay Time	$t_{d(off)}$		-	44	-	
Fall Time	t_f		-	21	-	

Reverse Diode Characteristics

Diode Forward Voltage	V_{SD}	$V_{GS}=0V, I_F=-2A$	-		-1.2	V
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Fig 1. Typical Output Characteristics

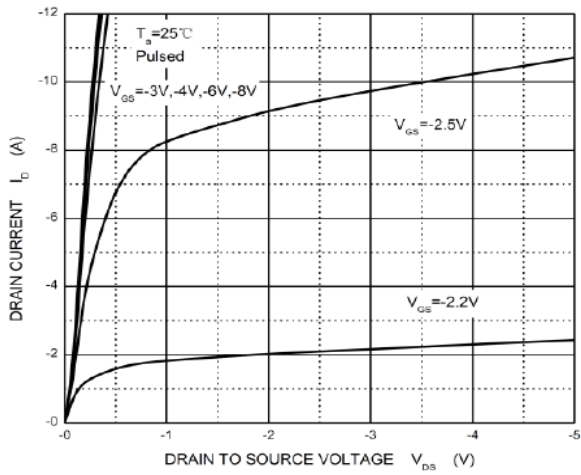


Figure 2. On-Resistance vs. Gate-Source Voltage

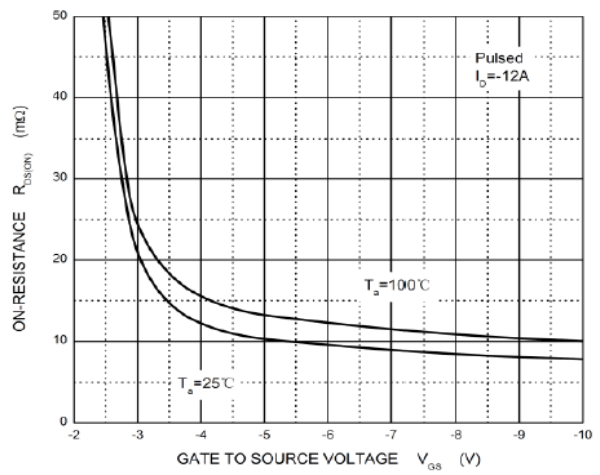


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

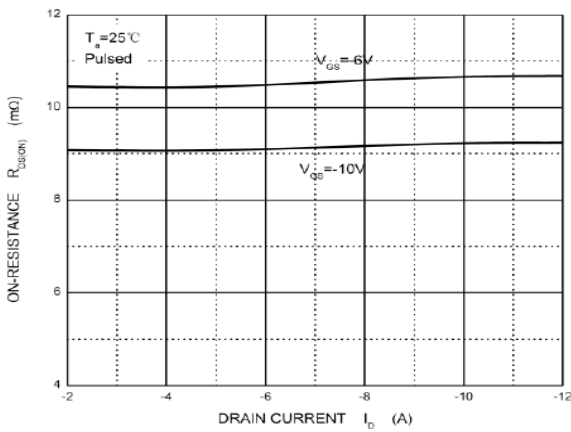


Figure 4. Thershold Voltage vs. Junction Temperature

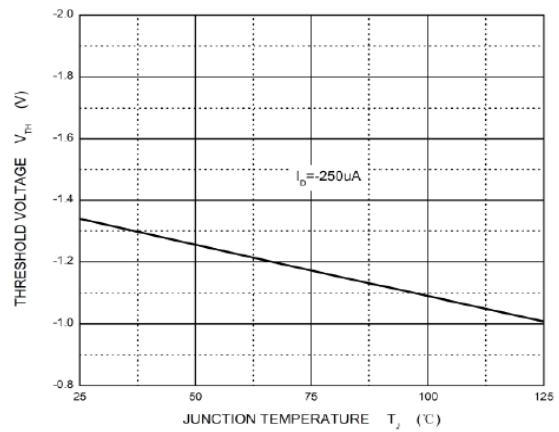


Figure 5. Typical Transfer Characteristics

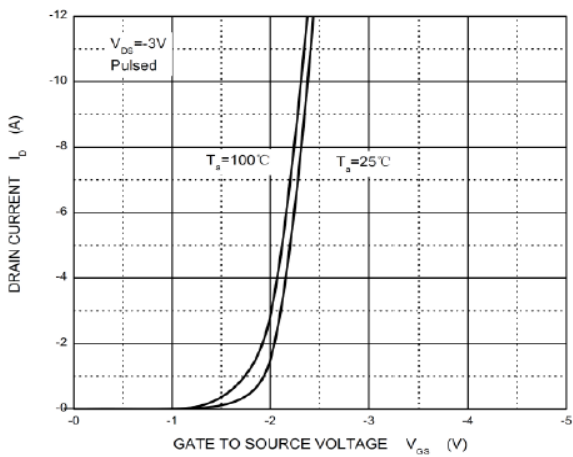
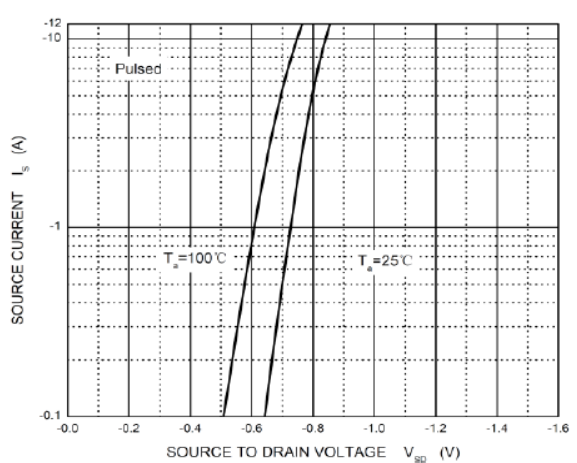
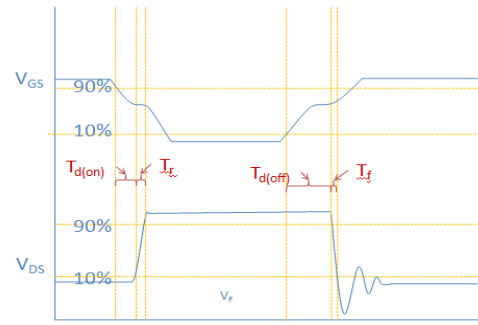
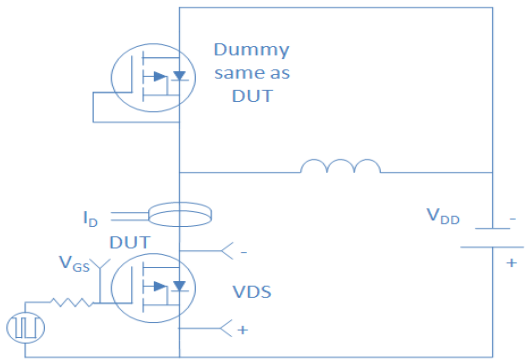


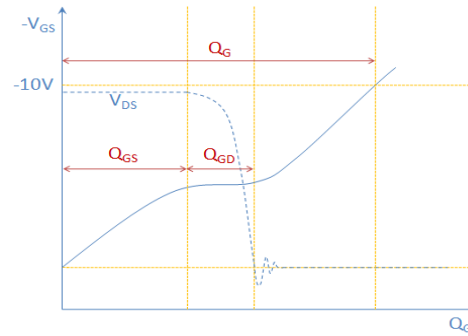
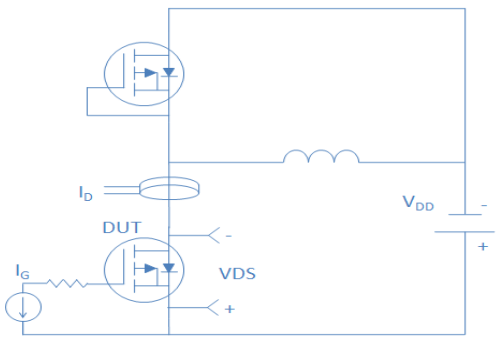
Figure 6. Typical Source-Drain Diode Forward Voltage



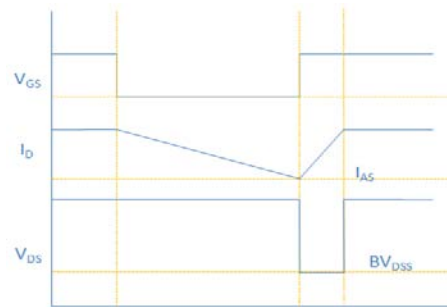
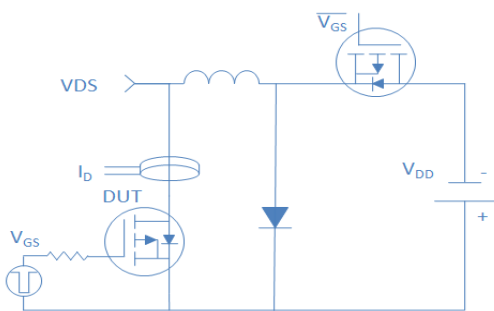
Inductive switching Test



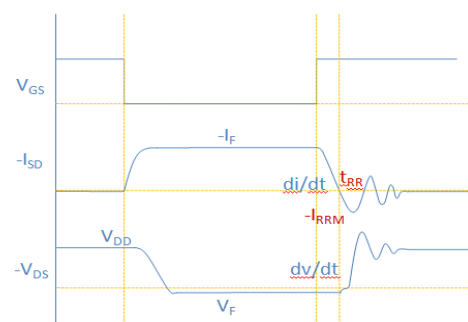
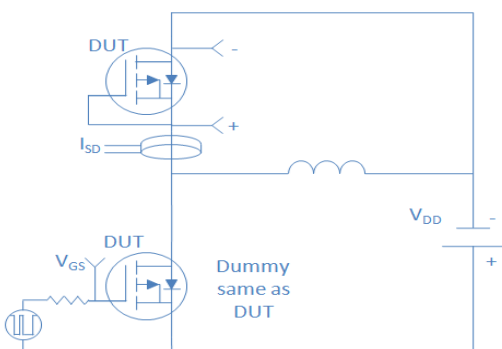
Gate Charge Test



Uclamped Inductive Switching (UIS) Test

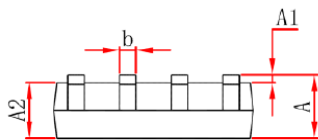
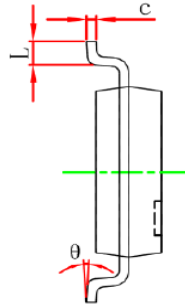
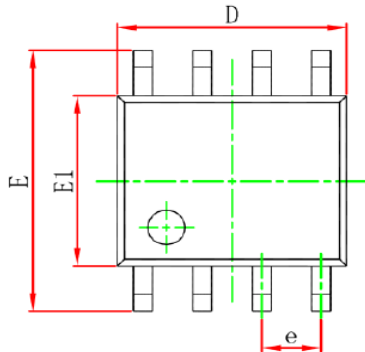


Diode Recovery Test



Package Outline

SOP-8, 8leads



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.007	0.010
D	4.800	5.000	0.189	0.197
e	1.270 (BSC)		0.050 (BSC)	
E	5.800	6.200	0.228	0.244
E1	3.800	4.000	0.150	0.157
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°